

**AMENDMENT**

**U.S. Appln. No. 10/765,931**

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

Claim 1. (Cancelled).

Claim 2. (Currently Amended) The solder deposition method according to claim 8, wherein said step of forming a dam includes the steps of:

forming a resin film on the surface of said substrate; and  
providing an opening part in said resin film so that a dam is formed around an electrode on a substrate.

Claim 3. (Currently Amended) The solder deposition method according to claim 8, wherein said dam is not removed after depositing solder.

Claim 4. (Currently Amended) The solder deposition method according to claim 8, wherein said substrate is a via-on-pad structured substrate.

Claims 5-7. (Cancelled).

Claim 8. (Previously Presented) A solder deposition method comprising the steps of:

forming a dam around an electrode on a substrate;  
applying a solder precipitating composition to said substrate; and

depositing solder on the surface of said electrode while heating said solder precipitating composition applied,

wherein said solder precipitating composition comprises a tin powder; and a complex of at least one member selected from the group consisting of silver ions and copper ions, and at

**AMENDMENT**

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least one member selected from the group consisting of aryl phosphines, alkyl phosphines and azoles.

Claim 9. (Previously Presented) A solder deposition method comprising the steps of:

forming a dam around an electrode on a substrate;

applying a solder precipitating composition to said substrate; and

depositing solder on the surface of said electrode while heating said solder precipitating composition applied,

wherein said solder precipitating composition comprises a tin powder and a salt of at least one metal selected from the group consisting of lead, copper and silver.

Claim 10. (Currently Amended) The solder deposition method according to claim 9, wherein said step of forming a dam includes the steps of:

forming a resin film on the surface of said substrate; and

providing an opening part in said resin film so that a dam is formed around an electrode on a substrate.

Claim 11. (Currently Amended) The solder deposition method according to claim 9, wherein said dam is not removed after depositing solder.

Claim 12. (Currently Amended) The solder deposition method according to claim 9, wherein said substrate is a via-on-pad structured substrate.